



566.38683CX1

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Masato YOSHIDA, et al.  
Serial No.: 10/042,271  
Filed: January 11, 2002  
For: ABRASIVE METHOD OF POLISHING TARGET MEMBER AND  
PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE  
Group: 3723  
Examiner: Shantese L. McDonald

**TERMINAL DISCLAIMER**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RECEIVED**

May 28, 2004

**JUN 07 2004**

Sir: **TECHNOLOGY CENTER R3700**

Petitioner, Hitachi Chemical Company, Ltd., having its place of business at 1-1, Nishishinjuku 2-chome, Shinjuku-ku, Tokyo, Japan, represents that it is the sole owner of the entire interest of U.S. Application Serial No. 10/042,271, filed January 11, 2002, for ABRASIVE METHOD OF POLISHING TARGET MEMBER AND PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE, and that the Assignment of all rights in connection therewith has been recorded at Reel 011094, Frame 0768.

Petitioner hereby disclaims all that portion of the term of any patent to be issued on the above-identified application subsequent to the expiration date of the full statutory term, defined in 35 U.S.C. 154 to 156 and 173, of U.S. Patent